RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

Data sheet

E-Duplexer
Small cell
LTE band 12

Series/type:	D7904
Ordering code:	B39741D7904D310
Date:	December 21, 2018
Version:	2.0

Table of contents

1 Application

- Enhanced Duplexer for LTE small cell systems (Band 12)
- High isolation > 60 dB min
- Usable pass band 17 MHz
- Low VSWR
- RX = uplink = 699 – 716 MHz
- TX = downlink = 729 – 746 MHz

2 Features

- Package size $8.1_{\pm 0.1}$ mm × $8.1_{\pm 0.1}$ mm
- Package height 1.1 mm (max.)
- Approximate weight 0.2 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

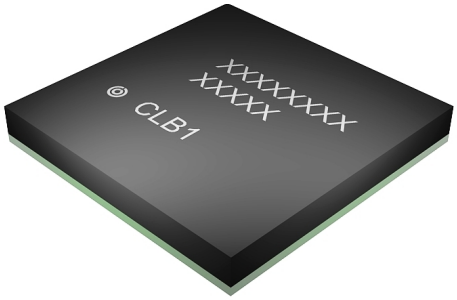
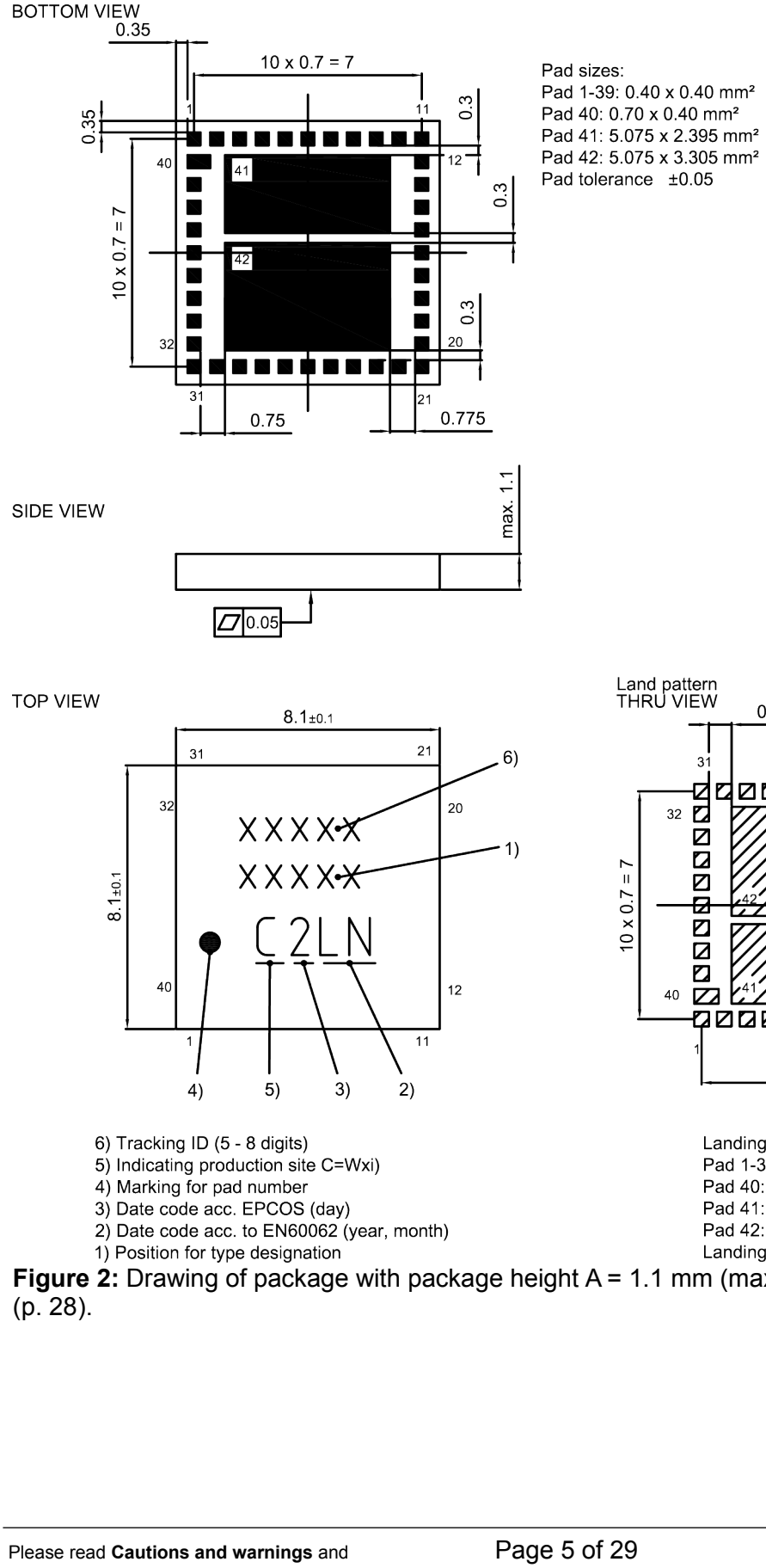


Figure 1: Picture of component with example of product marking.

3 Package



Pad sizes:
Pad 1-39: 0.40 x 0.40 mm²
Pad 40: 0.70 x 0.40 mm²
Pad 41: 5.075 x 2.395 mm²
Pad 42: 5.075 x 3.305 mm²
Pad tolerance ±0.05

6) Tracking ID (5 - 8 digits)
5) Indicating production site C=Wxi)
4) Marking for pad number
3) Date code acc. EPCOS (day)
2) Date code acc. to EN60062 (year, month)
1) Position for type designation

Landing pad sizes:
Pad 1-39: 0.45 x 0.45 mm²
Pad 40: 0.70 x 0.40 mm²
Pad 41: 5.125 x 2.445 mm²
Pad 42: 5.125 x 3.355 mm²
Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 1.1 mm (max.). See Sec. Package information (p. 28).

4 Pin configuration

- 3 TX
- 13 RX
- 29 ANT
- 1, 2, 4, 5, 6, 7, 8, 9, 10, 11, 12, 14, 15, 16, 17, 18, 19, 20, 21, 22, 23, 24, 25, 26, 27, 28, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 42 Ground

5 Matching circuit

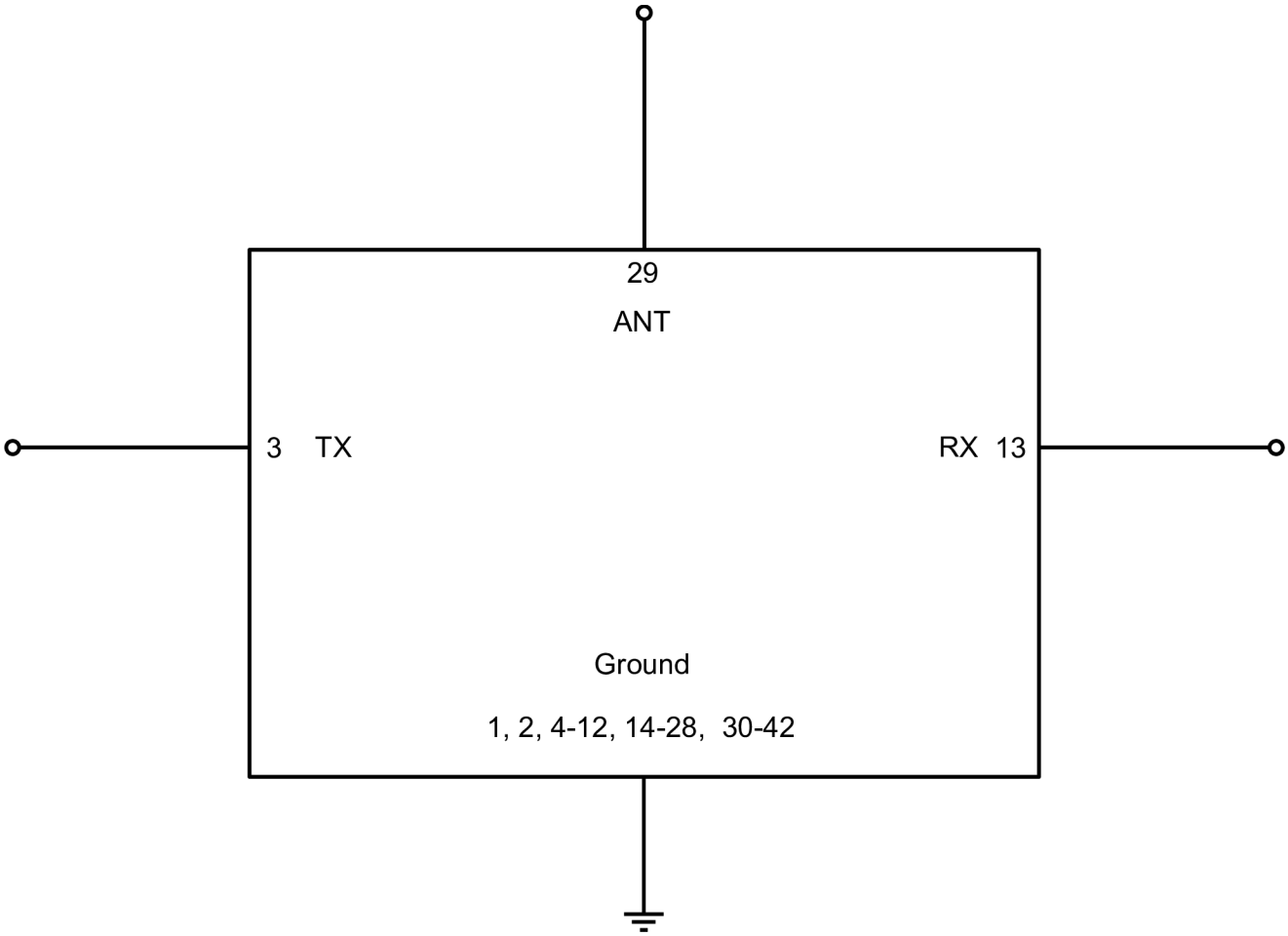


Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

6.1 TX – ANT

Temperature range for specification T_{SPEC} = −10 °C ... +85 °C
TX terminating impedance Z_{TX} = 50 Ω
ANT terminating impedance Z_{ANT} = 50 Ω
RX terminating impedance Z_{RX} = 50 Ω

Characteristics TX – ANT				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Center frequency			f_C	—	737.5	—	MHz
Average insertion attenuation			$\alpha_{INT,avg}$ [1]				
	729 ... 734	MHz		—	2.0	2.9	dB
	734 ... 741	MHz		—	2.0	2.7	dB
	741 ... 746	MHz		—	1.9	2.7	dB
Maximum insertion attenuation			α_{max}				
	729 ... 746	MHz		—	2.3	3.0	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	729 ... 746	MHz		—	0.6	1.4	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	729 ... 746	MHz		—	1.2	1.7	
@ ANT port	729 ... 746	MHz		—	1.2	1.7	
Maximum error vector magnitude			EVM_{max} [2]				
	731.4 ... 743.6	MHz		—	2.6	4.2	%
Minimum attenuation			α_{min}				
	50 ... 699	MHz		35	40	—	dB
	699 ... 716	MHz		45	54	—	dB
	777 ... 787	MHz		35	52	—	dB
	788 ... 798	MHz		35	46	—	dB
	824 ... 849	MHz		35	42	—	dB
	869 ... 894	MHz		35	41	—	dB
	1458 ... 1492	MHz		40	49	—	dB
	1574 ... 1606	MHz		40	51	—	dB
	1710 ... 1785	MHz		40	54	—	dB
	1850 ... 1915	MHz		40	54	—	dB
	1930 ... 1995	MHz		40	53	—	dB
	2187 ... 2238	MHz		40	50	—	dB
	2400 ... 2500	MHz		40	48	—	dB
	3550 ... 3800	MHz		35	42	—	dB
	5150 ... 5850	MHz		15	28	—	dB

[1] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.
[2] Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

Temperature range for specification	T_{SPEC}	= −40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – ANT				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Center frequency			f_C	—	737.5	—	MHz
Average insertion attenuation			$\alpha_{INT,avg}$ [1]				
	729 ... 734	MHz		—	2.0	2.9	dB
	734 ... 741	MHz		—	2.0	2.7	dB
	741 ... 746	MHz		—	1.9	2.7	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	729 ... 746	MHz		—	0.6	2.1	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	729 ... 746	MHz		—	1.2	1.7	
@ ANT port	729 ... 746	MHz		—	1.2	1.7	
Maximum error vector magnitude			EVM_{max} [2]				
	731.4 ... 743.6	MHz		—	2.6	4.5	%
Minimum attenuation			α_{min}				
	50 ... 699	MHz		35	40	—	dB
	699 ... 716	MHz		45	54	—	dB
	777 ... 787	MHz		35	52	—	dB
	788 ... 798	MHz		35	46	—	dB
	824 ... 849	MHz		35	42	—	dB
	869 ... 894	MHz		35	41	—	dB
	1458 ... 1492	MHz		40	49	—	dB
	1574 ... 1606	MHz		40	51	—	dB
	1710 ... 1785	MHz		40	54	—	dB
	1850 ... 1915	MHz		40	54	—	dB
	1930 ... 1995	MHz		40	53	—	dB
	2187 ... 2238	MHz		40	50	—	dB
	2400 ... 2500	MHz		40	48	—	dB
	3550 ... 3800	MHz		35	42	—	dB
	5150 ... 5850	MHz		15	28	—	dB

[1] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

[2] Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= −10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Center frequency			f_C	—	707.5	—	MHz
Average insertion attenuation			$\alpha_{INT,avg}$ [1]				
	699 ... 704	MHz		—	2.0	2.6	dB
	704 ... 711	MHz		—	2.0	3.1	dB
	711 ... 716	MHz		—	2.9	3.8	dB
Maximum insertion attenuation			α_{max}				
	699 ... 714.75	MHz		—	3.2	4.3	dB
	714.75 ... 716	MHz		—	3.2	5.7	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	699 ... 714.75	MHz		—	1.2	3.2	dB
	699 ... 716	MHz		—	1.2	3.6	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	699 ... 716	MHz		—	1.2	1.7	
@ RX port	699 ... 716	MHz		—	1.2	1.7	
Maximum error vector magnitude			EVM_{max} [2]				
	701.4 ... 713.6	MHz		—	2.8	6.5	%
Minimum attenuation			α_{min}				
	100 ... 600	MHz		45	58	—	dB
	693 ... 694.7	MHz		5	15	—	dB
	721 ... 723	MHz		5	13	—	dB
	723 ... 728	MHz		15	26	—	dB
	728 ... 798	MHz		42	52	—	dB
	869 ... 894	MHz		45	54	—	dB
	1398 ... 1432	MHz		50	67	—	dB
	1574 ... 1606	MHz		50	66	—	dB
	1710 ... 1785	MHz		50	65	—	dB
	1850 ... 1915	MHz		50	63	—	dB
	1930 ... 1995	MHz		50	64	—	dB
	2110 ... 2200	MHz		40	52	—	dB
	2400 ... 2500	MHz		50	66	—	dB
	3550 ... 3800	MHz		35	46	—	dB
	5150 ... 5850	MHz		25	41	—	dB

[1] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

[2] Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

Temperature range for specification	T_{SPEC}	= −40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Center frequency			f_C	—	707.5	—	MHz
Average insertion attenuation			$\alpha_{INT,avg}$ [1]				
	699 ... 704	MHz		—	2.0	2.6	dB
	704 ... 711	MHz		—	2.0	3.1	dB
	711 ... 716	MHz		—	2.9	3.8	dB
Amplitude ripple (p-p)			Δα				
	699 ... 714.75	MHz		—	1.2	3.6 [2]	dB
	699 ... 716	MHz		—	1.2	10	dB
	699 ... 716	MHz		—	1.2	4.4 [2]	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	699 ... 716	MHz		—	1.2	1.7	
@ RX port	699 ... 716	MHz		—	1.2	1.7	
Minimum attenuation			α_{min}				
	100 ... 600	MHz		45	58	—	dB
	693 ... 694.7	MHz		4	15	—	dB
	721 ... 723	MHz		4	13	—	dB
	723 ... 728	MHz		8	26	—	dB
	728 ... 798	MHz		40	50	—	dB
	869 ... 894	MHz		45	54	—	dB
	1398 ... 1432	MHz		50	67	—	dB
	1574 ... 1606	MHz		50	66	—	dB
	1710 ... 1785	MHz		50	65	—	dB
	1850 ... 1915	MHz		50	63	—	dB
	1930 ... 1995	MHz		50	64	—	dB
	2110 ... 2200	MHz		40	52	—	dB
	2400 ... 2500	MHz		50	66	—	dB
	3550 ... 3800	MHz		35	46	—	dB
	5150 ... 5850	MHz		25	41	—	dB

[1] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

[2] Valid for temperature T = −10 °C...+95 °C.

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= −10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Minimum isolation							
	699... 716	MHz	α_{min}	60	66	—	dB
	699... 716	MHz	$\alpha_{INT,min}$ [1)]	60	69	—	dB
	729... 746	MHz	α_{min}	60	65	—	dB
	729... 746	MHz	$\alpha_{INT,min}$ [1)]	60	68	—	dB

1) Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

Temperature range for specification	T_{SPEC}	= −40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Minimum isolation							
	699... 716	MHz	α_{min}	60	66	—	dB
	699... 716	MHz	$\alpha_{INT,min}$ [1)]	60	69	—	dB
	729... 746	MHz	α_{min}	58	65	—	dB
	729... 746	MHz	$\alpha_{INT,min}$ [1)]	60	68	—	dB

1) Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

7 Maximum ratings

Operable temperature	T_{OP} = −40 °C ... +95 °C	
Storage temperature	T_{STG} [1] = −40 °C ... +95 °C	
DC voltage	$\lvert V_{DC} \rvert$ [2] = 0 V (max.)	
ESD voltage		
	V_{ESD} [3] = 100 V (max.)	Machine model.
	V_{ESD} [4] = 100 V (max.)	Human body model.
Input power	P_{IN}	
@ TX port: 729 ... 746 MHz	31 dBm [5], [6]	5 MHz LTE downlink signal for 100000 h @ 55 °C. P_{IN} average – 42 dBm peak. Source and load impedance 50 Ω.
@ TX port: other frequency ranges	10 dBm	Source and load impedance 50 Ω.

1) Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
2) In case of applied DC voltage blocking capacitors are mandatory.
3) According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.
4) According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.
5) Expected lifetime according to accelerated power durability test and wear out models.
6) T_{SPEC} is the ambient temperature of the PCB at component position. Specified min./max values from section 6 "characteristics" for maximum input power 31 dBm are valid for temperature up to 65 °C.

8 Transmission coefficients

8.1 TX – ANT

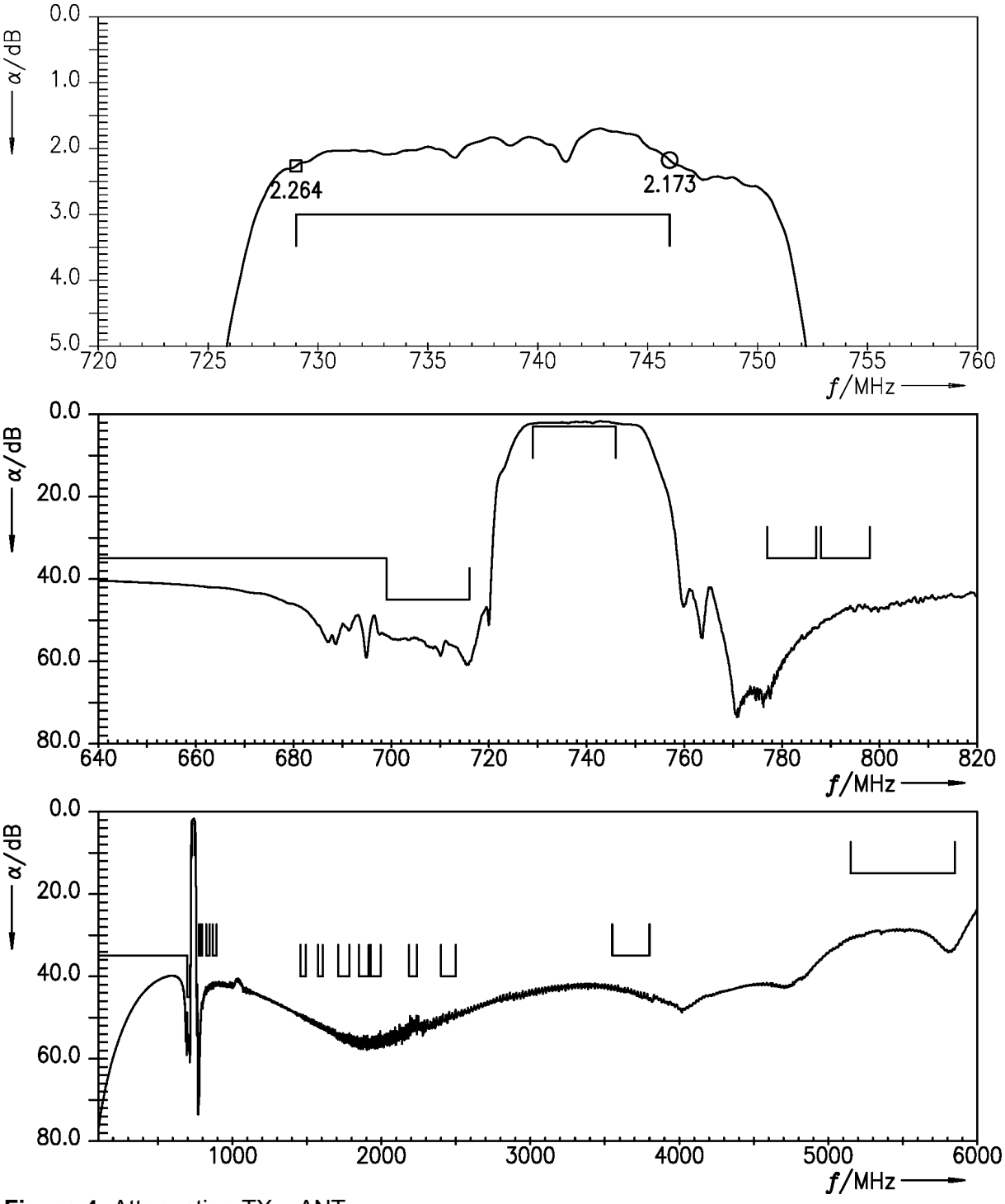


Figure 4: Attenuation TX – ANT.

8.2 ANT – RX

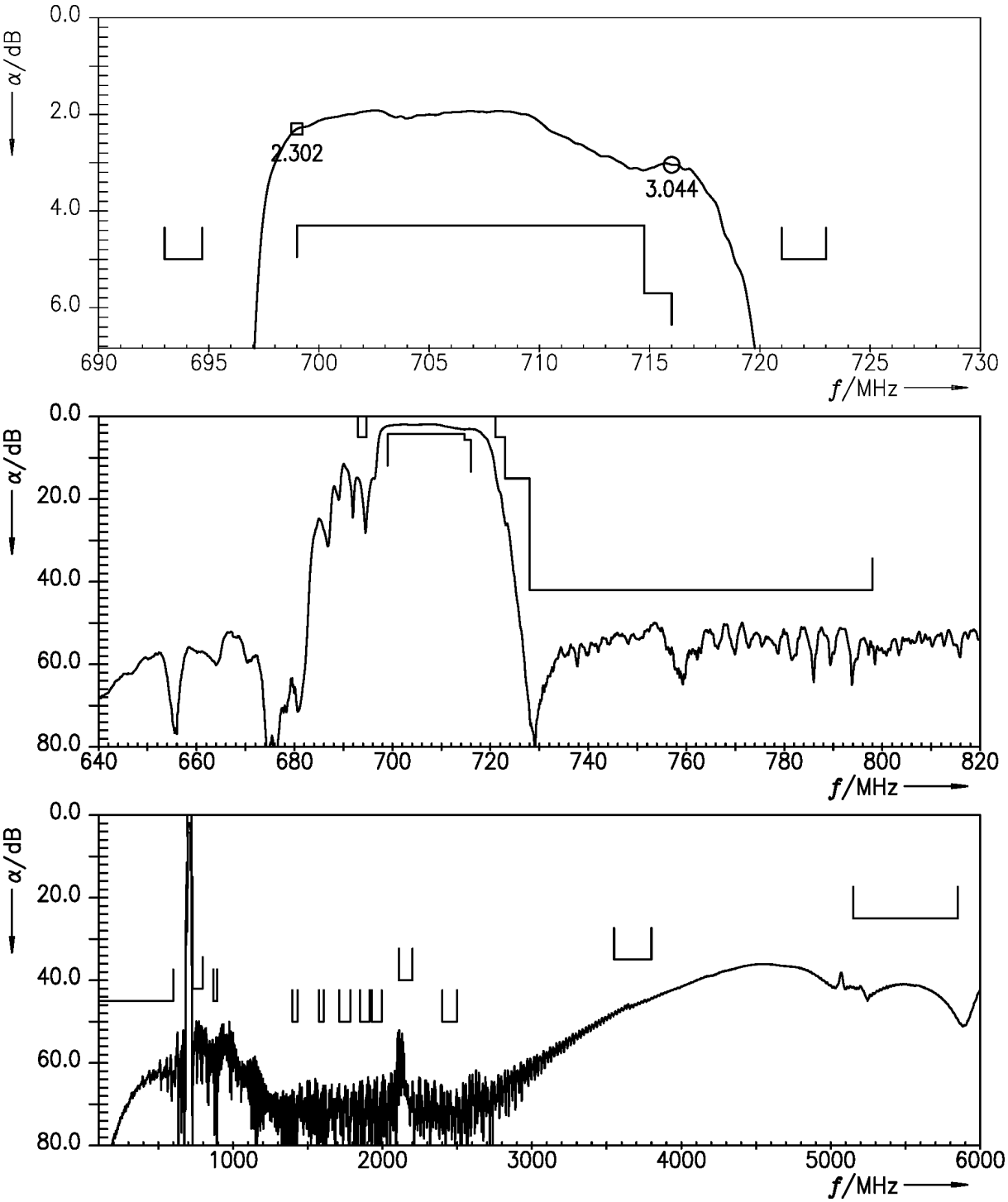


Figure 5: Attenuation ANT – RX.

8.3 TX – RX

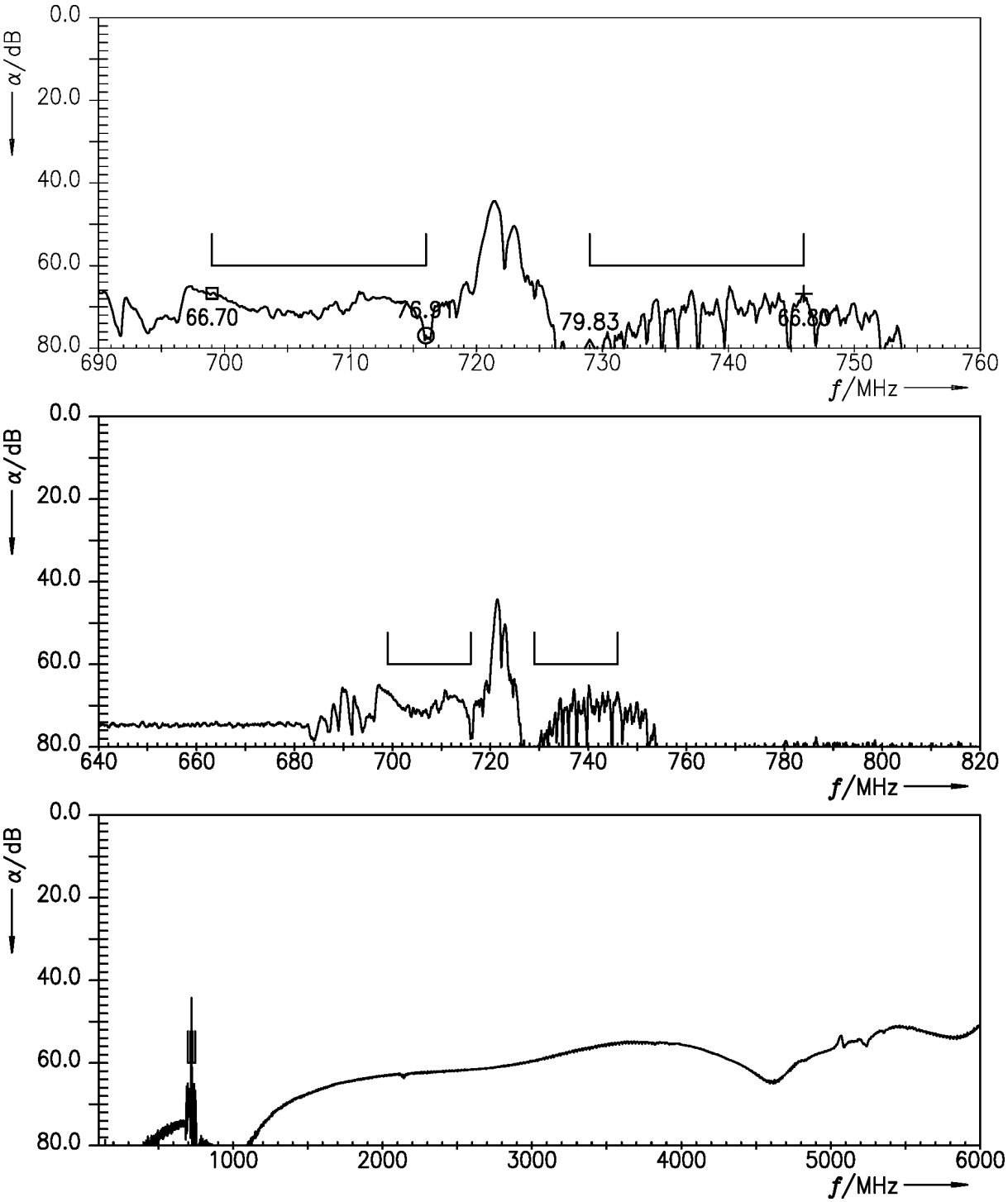


Figure 6: Isolation TX – RX.

9 Reflection coefficients

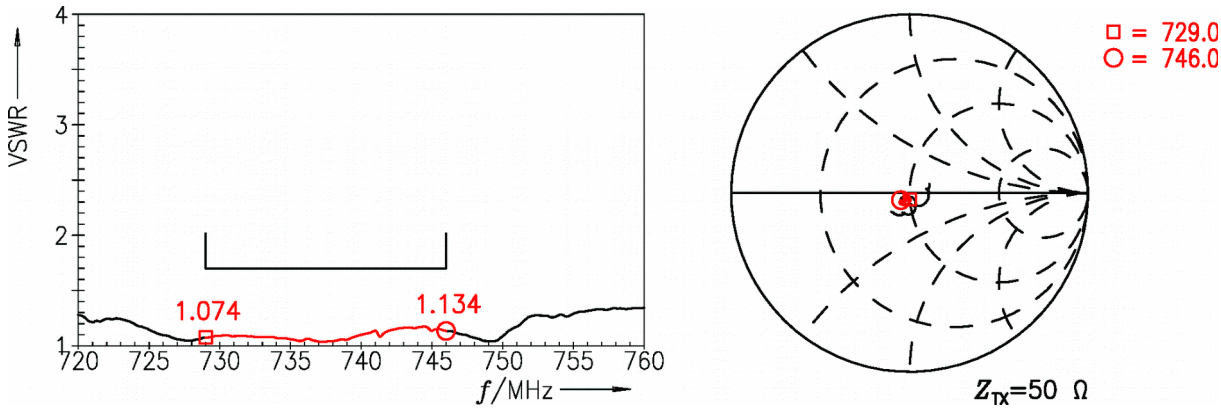


Figure 7: Reflection coefficient at TX port.

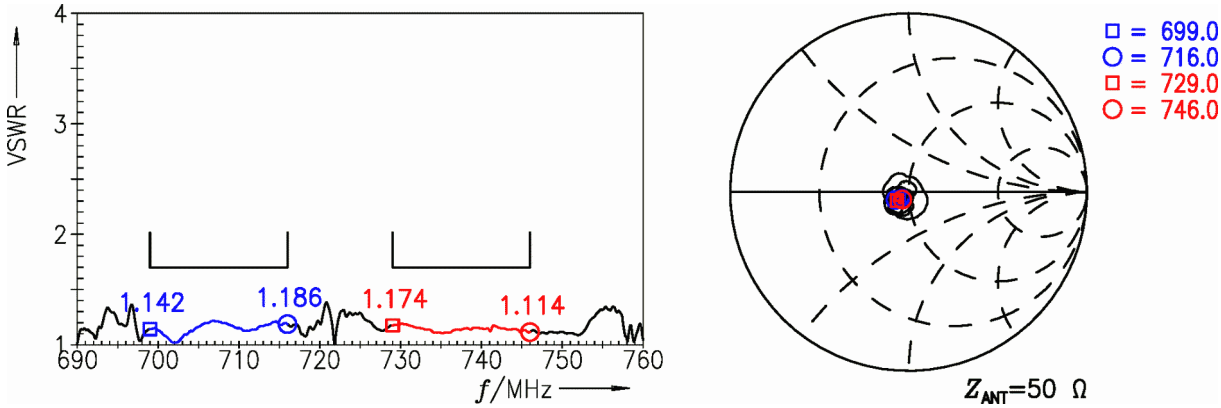


Figure 8: Reflection coefficient at ANT port.

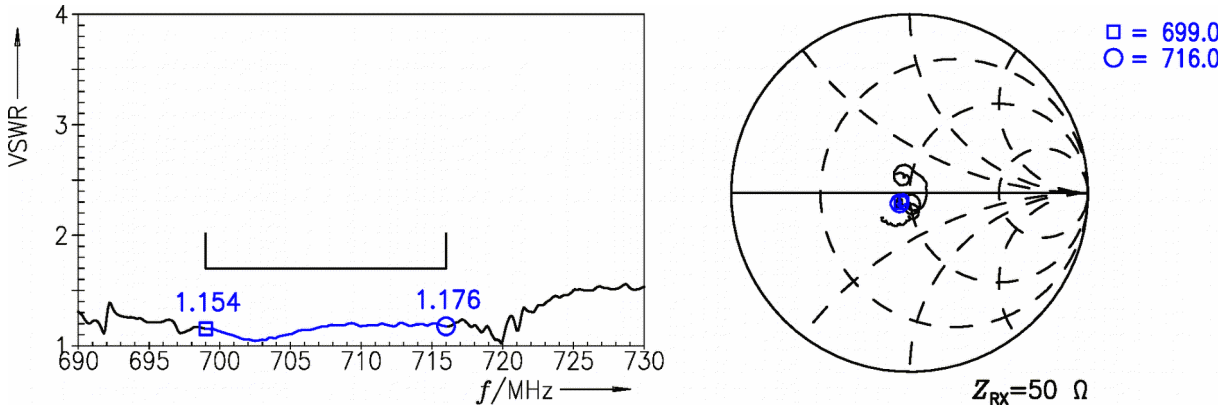


Figure 9: Reflection coefficient at RX port.

10 EVMs

10.1 TX – ANT

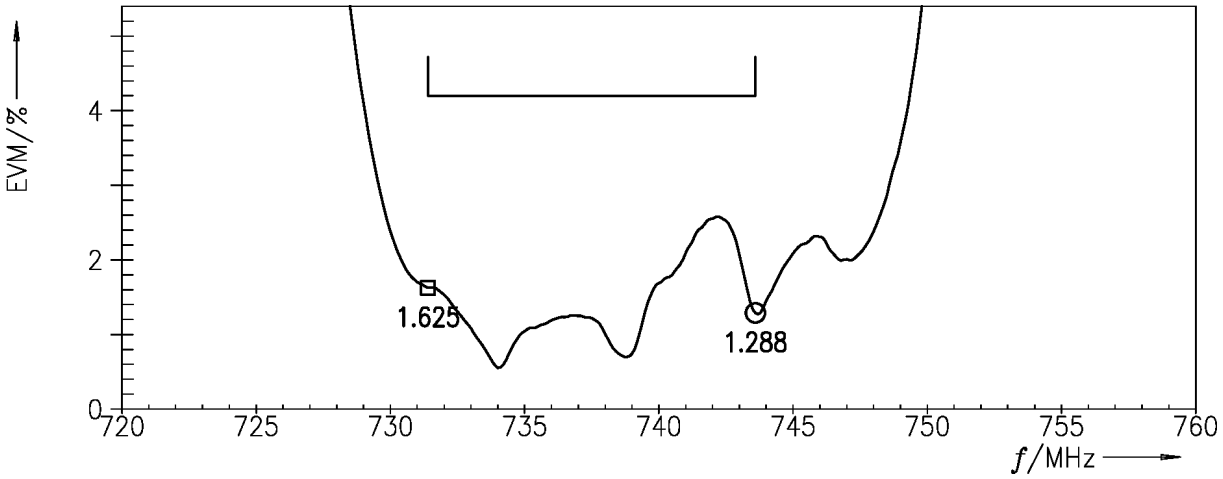


Figure 10: Error vector magnitude TX – ANT.

10.2 ANT – RX

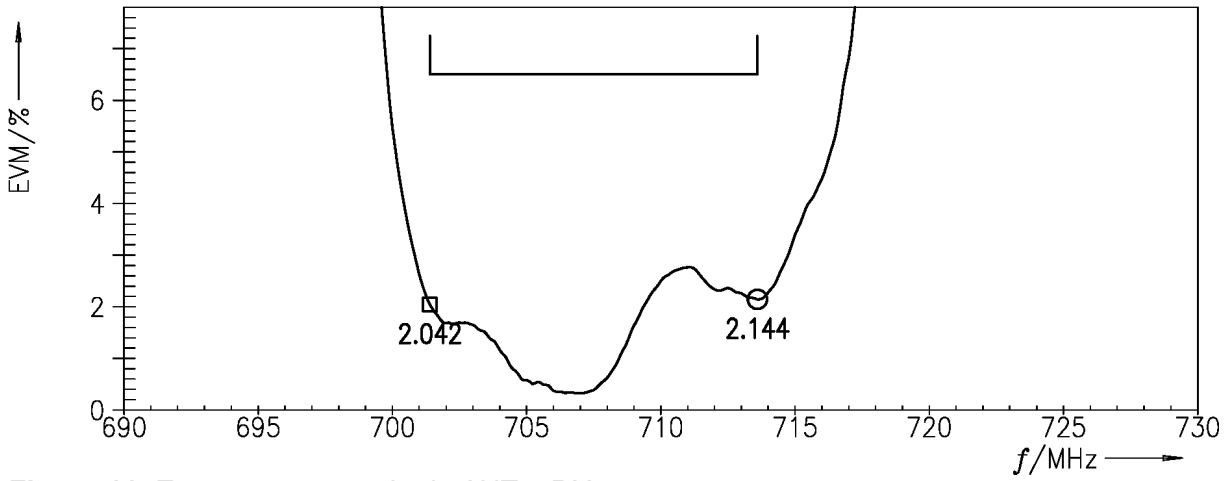


Figure 11: Error vector magnitude ANT – RX.

11 Packing material

11.1 Tape

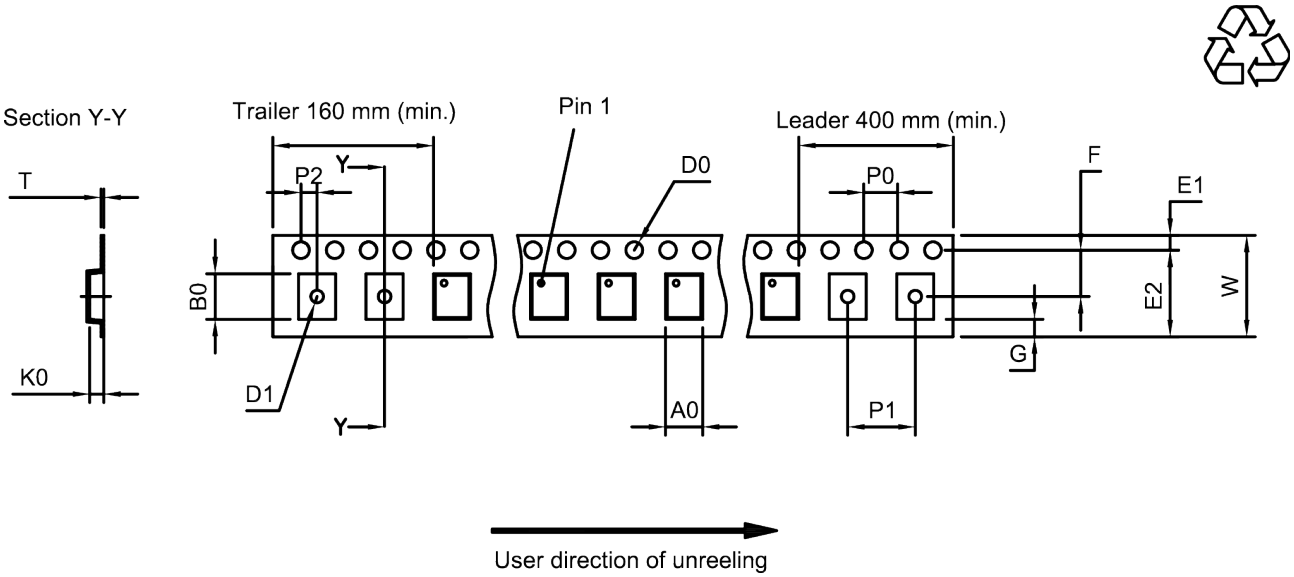


Figure 12: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A_0	8.4±0.05 mm
B_0	8.4±0.05 mm
D_0	1.5+0.1/−0 mm
D_1	1.5 mm (min.)
E_1	1.75±0.1 mm

E_2	14.25 mm (min.)
F	7.5±0.1 mm
G	0.75 mm (min.)
K_0	1.3±0.1 mm
P_0	4.0±0.1 mm

P_1	12.0±0.1 mm
P_2	2.0±0.1 mm
T	0.3±0.05 mm
W	16.0+0.3/−0.1 mm

Table 1: Tape dimensions.

11.2 Reel with diameter of 330 mm

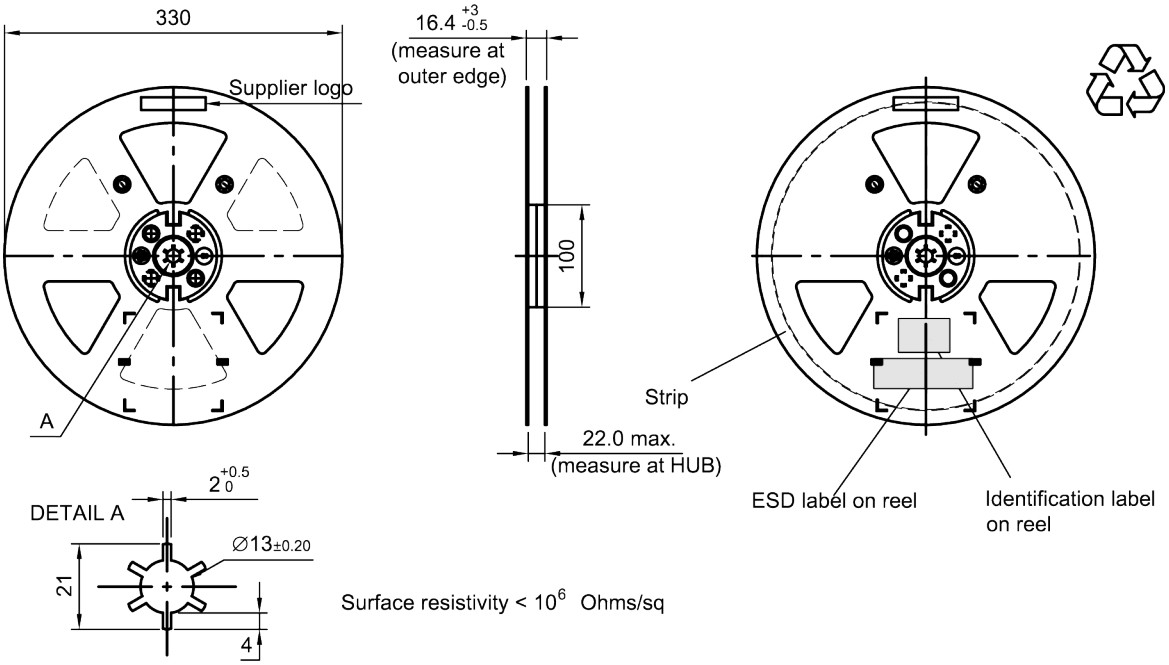


Figure 13: Drawing of reel (first-angle projection) with diameter of 330 mm.

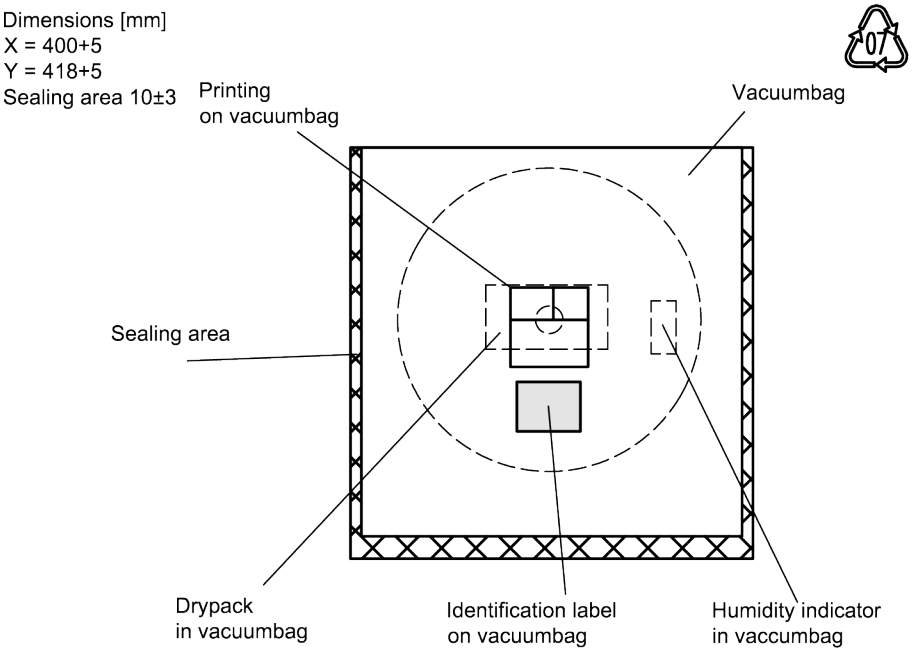


Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

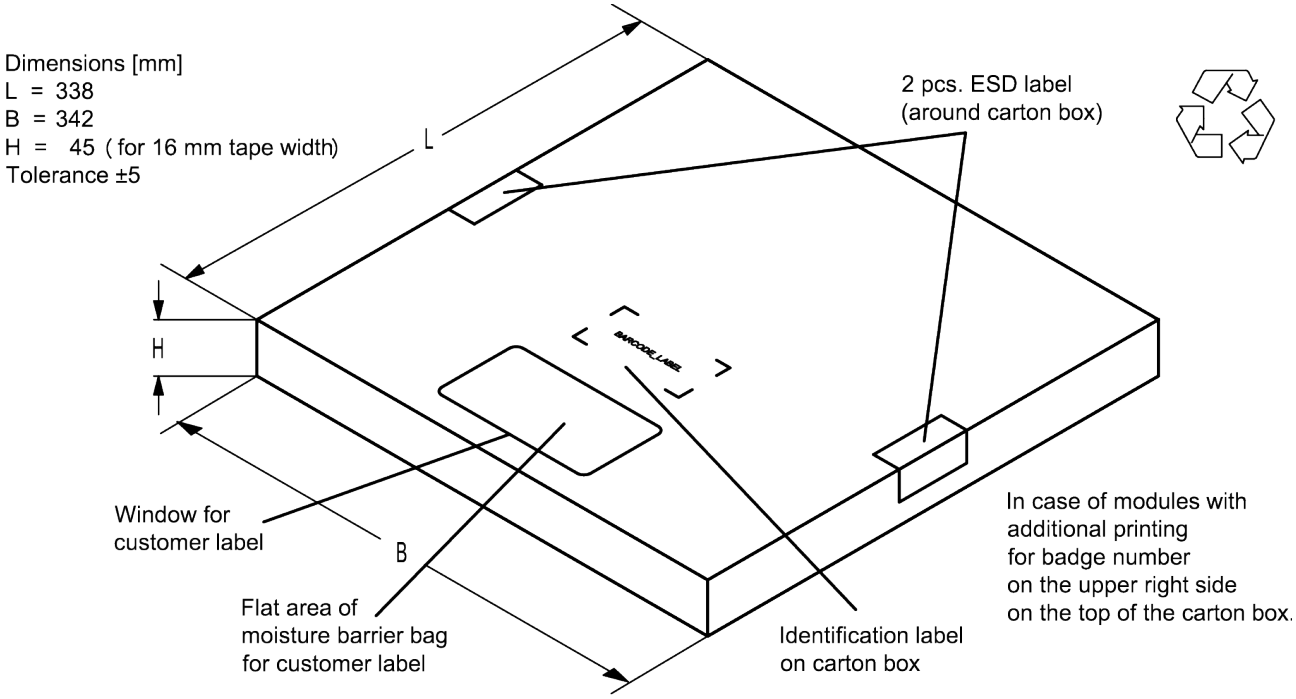


Figure 15: Drawing of folding box for reel with diameter of 330 mm.

12 Marking

Products are marked with tracking number (5 or 8 characters), type designator (5 characters), as well as production location and date code (4 characters). The marking corresponds to one of the following schemes:

XXXXX	5-character tracking number
XXXXX	5-character type designator
M5C6	1-character location code + 3-character date code (example)

Table 2: Marking for 5-character tracking number (standard).

XXXXXXXX	8-character tracking number
XXXXX	5-character type designator
M5C6	1-character location code + 3-character date code (example)

Table 3: Marking for 8-character tracking number.

???	
XXXXXXXX	8-character tracking number
XXXXX	5-character type designator
M5C6	1-character location code + 3-character date code (example)

Table 4: Marking for 8-character tracking number with 4 lines.

- Tracking number: *t.b.d.*

- Type designator: The 5-character type designator of the ordering code is used for the marking.

  Example: B3xxxx**D1234**xxxx

- Production-location and date code: The production-location is encoded in the first character according to Table 5. The production date code is encoded in the last three characters according to Table 6.

Code:	M or no letter	J	C	H
Location:	Munich	Singapore	Wuxi	SAE, Hong Kong

Table 5: Production location code.

1st digit (day)					
Day	Code	Day	Code	Day	Code
1	1	11	A	21	M
2	2	12	B	22	N
3	3	13	C	23	P
4	4	14	D	24	R
5	5	15	E	25	S
6	6	16	F	26	T
7	7	17	H	27	U
8	8	18	J	28	V
9	9	19	K	29	W
10	0	20	L	30	X
				31	Z

2nd digit (year)			
Year	Code	Year	Code
2010	A	2022	P
2011	B	2023	R
2012	C	2024	S
2013	D	2025	T
2014	E	2026	U
2015	F	2027	V
2016	H	2028	W
2017	J	2029	X
2018	K	2030	Z
2019	L	2031	A
2020	M	2032	B
2021	N	and so on	

3rd digit (month)			
Month	Code	Month	Code
Jan	1	Jul	7
Feb	2	Aug	8
Mar	3	Sep	9
Apr	4	Oct	0
May	5	Nov	N
Jun	6	Dec	D

Table 6: Production date code.

Example of how to decode production location and date code:

Code: **M 5 C 6**

Location: M → Munich
Day: 5 → 5th
Year: C → 2012
Month: 6 → June

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 7: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

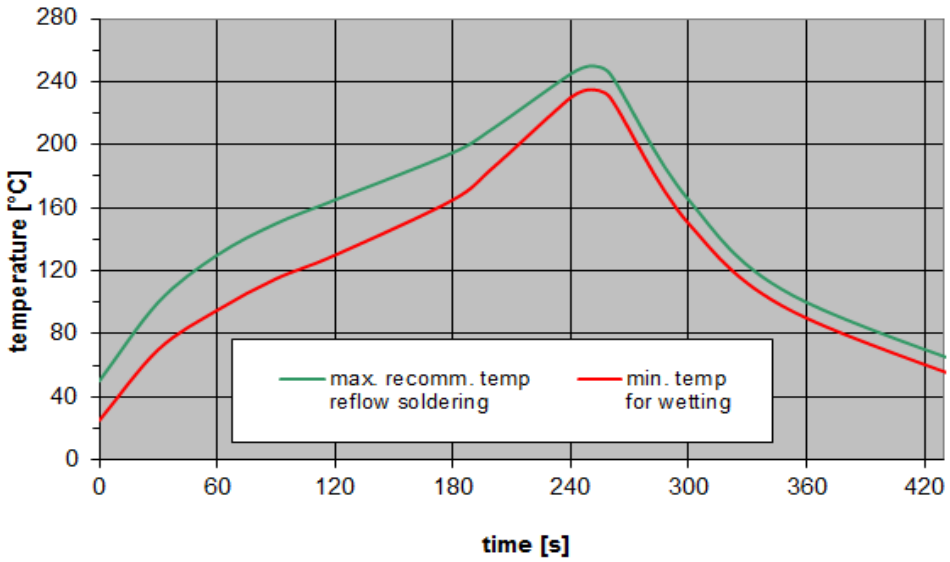


Figure 16: Recommended reflow profile for convection and infrared soldering – lead-free solder.

14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3 Ordering codes and packing units

Ordering code	Packing unit
B39741D7904D310	3000 pcs

Table 8: Ordering codes and packing units.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.rf360jv.com/material). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available.
   The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.